

EUGB24-35.328M-I2

[Click part number to visit Part Number Details page](#)

REGULATORY COMPLIANCE (Data Sheet downloaded on Oct 24, 2017)


[Click badges to download compliance docs](#)

Regulatory Compliance standards are subject to updates by governing bodies. Click the badges to download the latest compliance docs for this part number directly from Ecliptek.



ITEM DESCRIPTION

Quartz Crystal Resonator HC49/U Thru-Hole Metal Resistance Weld Seal 35.328MHz $\pm 15\text{ppm}$ at 25°C, $\pm 30\text{ppm}$ over 0°C to +70°C 24pF Parallel Resonant

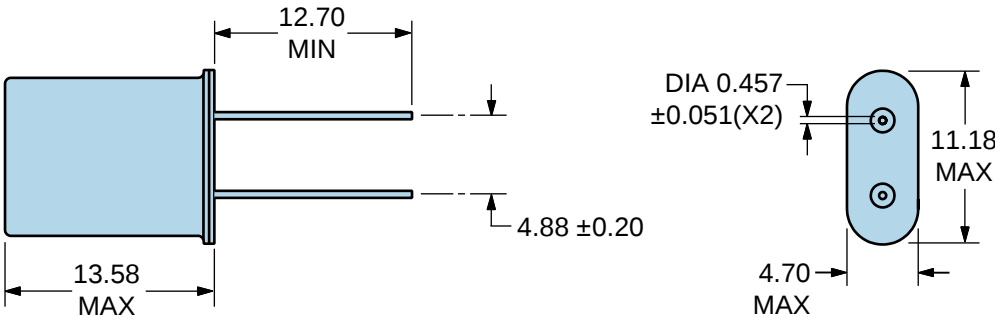
ELECTRICAL SPECIFICATIONS

Nominal Frequency	35.328MHz
Frequency Tolerance/Stability	$\pm 15\text{ppm}$ at 25°C, $\pm 30\text{ppm}$ over 0°C to +70°C
Aging at 25°C	$\pm 5\text{ppm/year}$ Maximum
Load Capacitance	24pF Parallel Resonant
Shunt Capacitance	7pF Maximum
Equivalent Series Resistance	40 Ohms Maximum
Mode of Operation	AT-Cut Third Overtone
Drive Level	2mWatts Maximum
Storage Temperature Range	-40°C to +125°C
Insulation Resistance	500 Megaohms Minimum (Measured at 100Vdc)

EUGB24-35.328M-I2

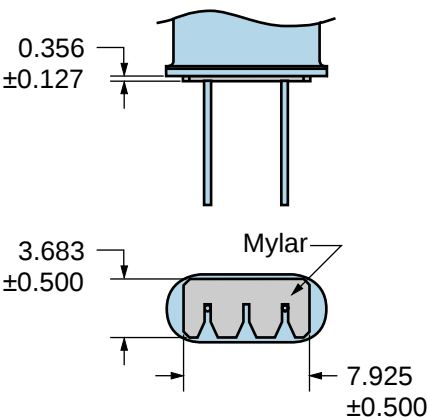
 Click part number to visit
Part Number Details page

MECHANICAL DIMENSIONS (all dimensions in millimeters)



LINE	MARKING
1	ECLIPTEK
2	E35.328M <i>E=Configuration Designator</i>
3	XX <i>XX=Ecliptek Manufacturing Identifier</i>

Value Added Option - Mylar Insulator Tab

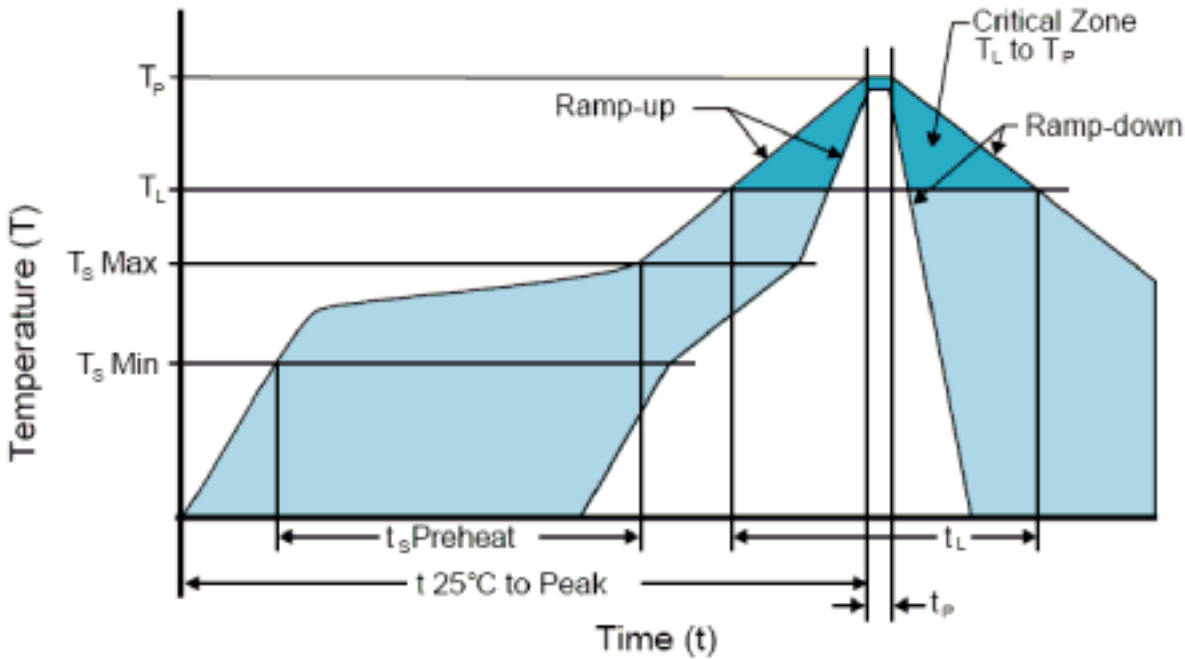


All dimensions are in millimeters

EUGB24-35.328M-I2

[Click part number to visit Part Number Details page](#)

Recommended Solder Reflow Methods



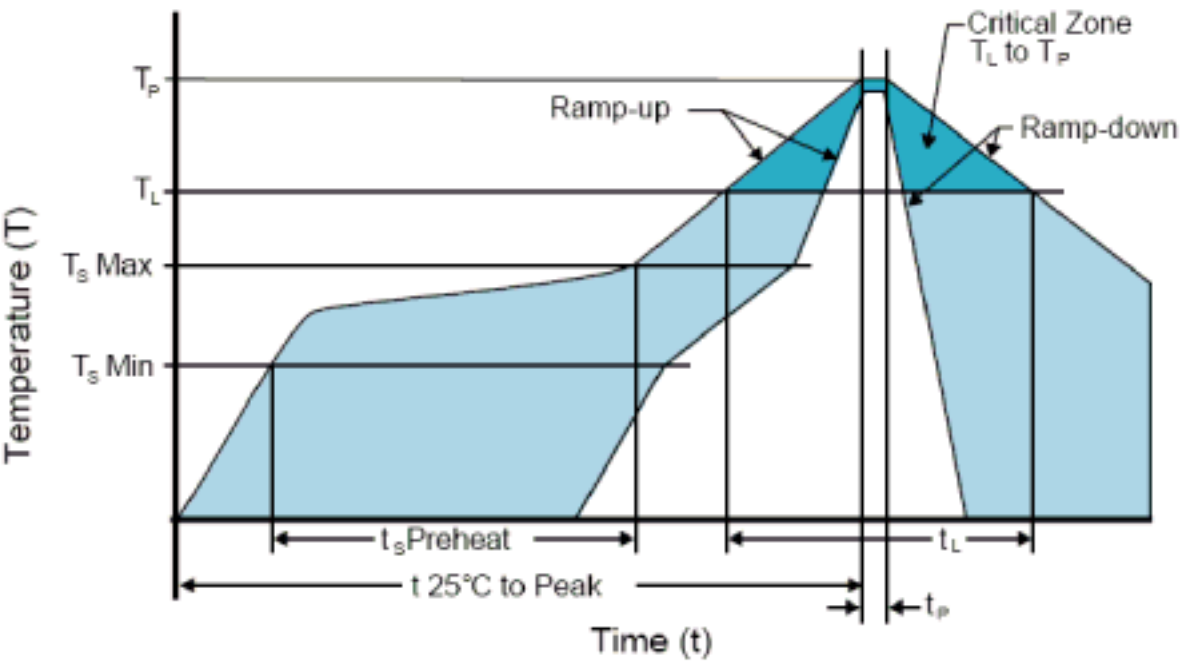
High Temperature Solder Bath (Wave Solder)

TS MAX to TL (Ramp-up Rate)	3°C/Second Maximum
Preheat	
- Temperature Minimum (TS MIN)	150°C
- Temperature Typical (TS TYP)	175°C
- Temperature Maximum (TS MAX)	200°C
- Time (ts MIN)	60 - 180 Seconds
Ramp-up Rate (TL to TP)	3°C/Second Maximum
Time Maintained Above:	
- Temperature (TL)	217°C
- Time (tL)	60 - 150 Seconds
Peak Temperature (TP)	260°C Maximum for 10 Seconds Maximum
Target Peak Temperature (TP Target)	250°C +0/-5°C
Time within 5°C of actual peak (tp)	20 - 40 Seconds
Ramp-down Rate	6°C/Second Maximum
Time 25°C to Peak Temperature (t)	8 Minutes Maximum
Moisture Sensitivity Level	Level 1
Additional Notes	Temperatures shown are applied to back of PCB board and device leads only.

EUGB24-35.328M-I2

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Recommended Solder Reflow Methods



Low Temperature Solder Bath (Wave Solder)

TS MAX to TL (Ramp-up Rate)	5°C/Second Maximum
Preheat	
- Temperature Minimum (TS MIN)	N/A
- Temperature Typical (TS TYP)	150°C
- Temperature Maximum (TS MAX)	N/A
- Time (ts MIN)	30 - 60 Seconds
Ramp-up Rate (TL to TP)	5°C/Second Maximum
Time Maintained Above:	
- Temperature (TL)	150°C
- Time (tL)	200 Seconds Maximum
Peak Temperature (TP)	245°C Maximum
Target Peak Temperature (TP Target)	245°C Maximum 1 Time / 235°C Maximum 2 Times
Time within 5°C of actual peak (tp)	5 Seconds Maximum 1 Time / 15 Seconds Maximum 2 Times
Ramp-down Rate	5°C/Second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1
Additional Notes	Temperatures shown are applied to back of PCB board and device leads only.

Low Temperature Manual Soldering